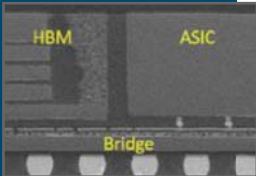


# Advanced Packaging Update: Market and Technology Trends

Vol. 2-0723



The second volume of the Advanced Packaging Update includes an analysis of OSAT financials; AI packaging trends; die-to-wafer hybrid bonding applications and challenges; and RF packaging trends. An updated analysis of build-up substrate supply and demand is presented. The status of glass core for substrates is included. TechSearch International's annual survey on substrate design rules is featured, with special coverage of suppliers of laminate flip chip BGA and CSP substrates worldwide. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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